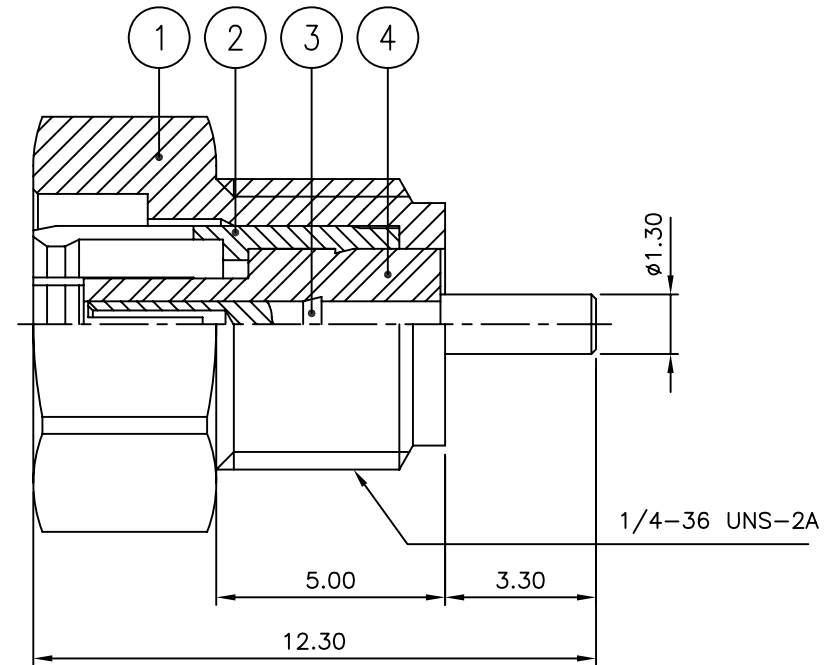
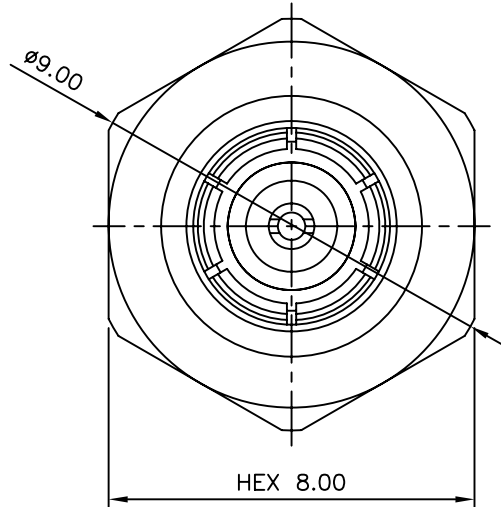


REVISION						
REV	DESCRIPTION			DRAWN	APPR	DATE
IR	Initial Registration			M.H.SONG	I.C.KIM	2014.01.14.
1	[설번처리 No.201504-0003] JACK 표준화 치수 적용 BOM구성 변경			H.J.LEE	I.C.KIM	2015.04.22.



4	INSULATOR	1	TEFLON		DIN02042-N/1
3	CONTACT	1	BeCu	Gold Plate	DCT03039-5/1
2	JACK	1	MBsBD	Nickel Plate	DJA00159-5/5 DJA00159-5/2
1	BODY	1	MBsBD	Nickel Plate	DBD03115-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2015. 04. 22.			 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017	
	Angle	APPROVED BY	I.C.KIM			
	±1°	CHECKED BY				
MATERIAL		DRAWN BY	H.J.LEE		TITLE SMBL50 SOLDER END PB (F/F)	
FINISH		SCALE	UNIT			
		6/1	mm		A4	
					DWG NO. CN02833-7/2	
					REVISION 1	SHEET 1 of 1